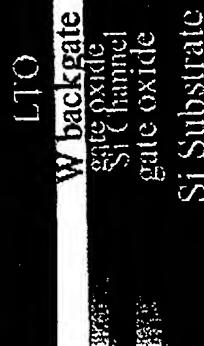


bonding



handle wafer



handle wafer

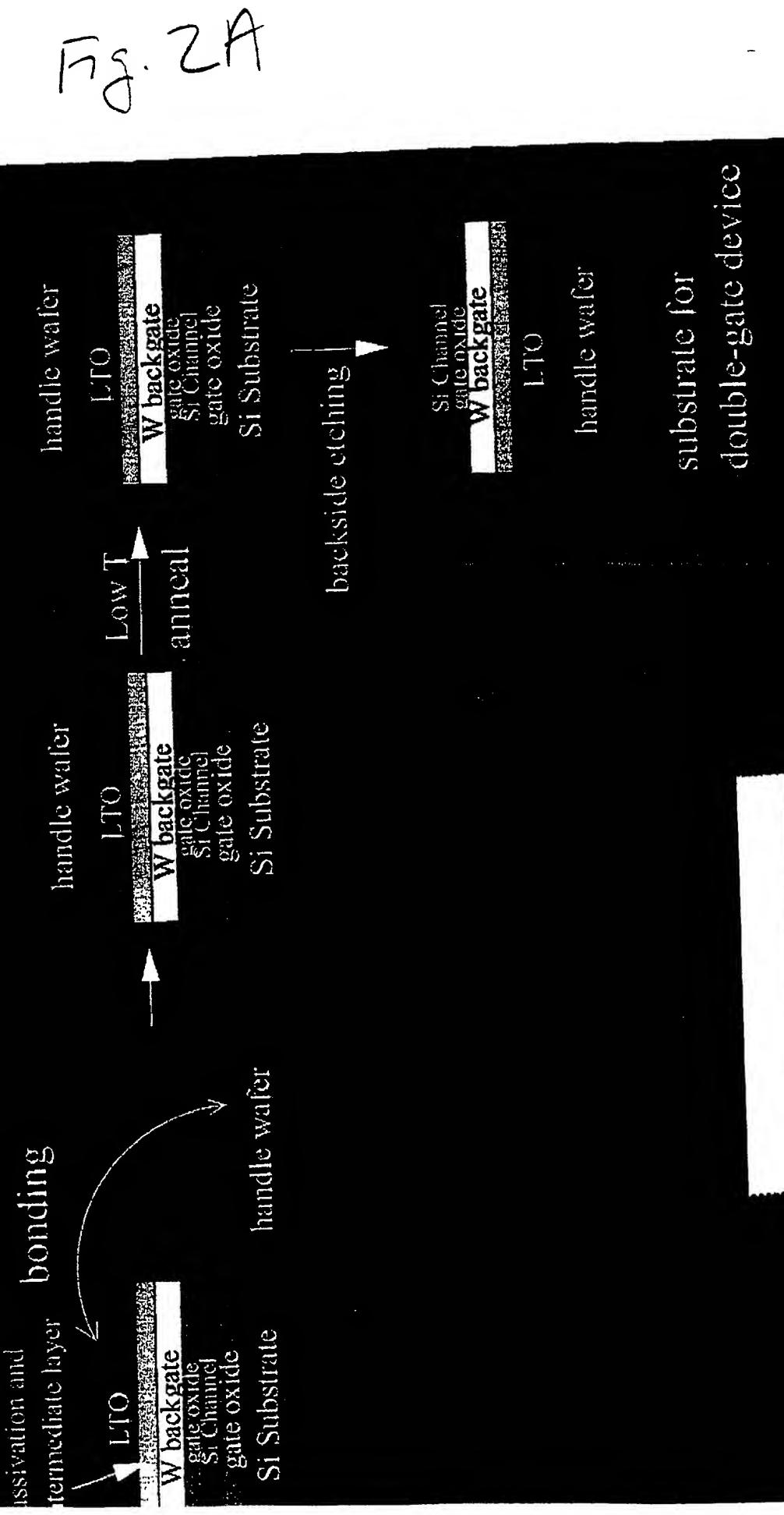
High T
anneal



LTO

Si Channel
gate oxide
Si Substrate

delamination



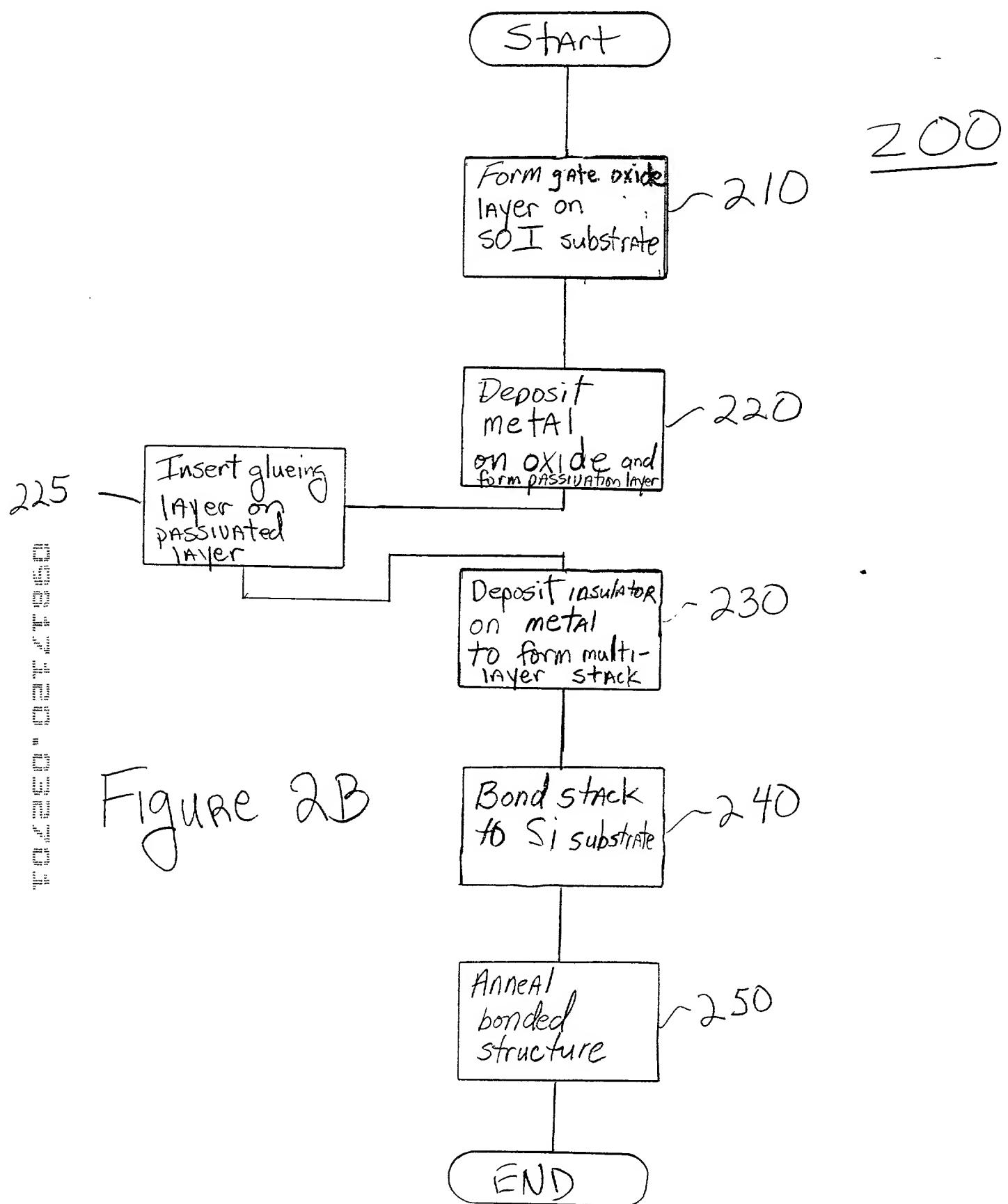


Fig 3 (a)

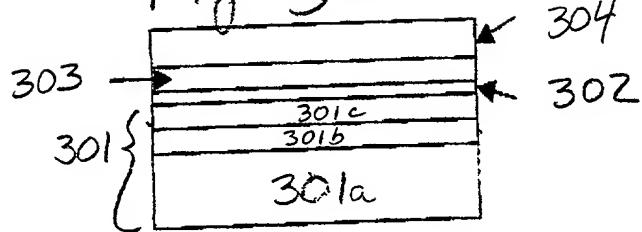
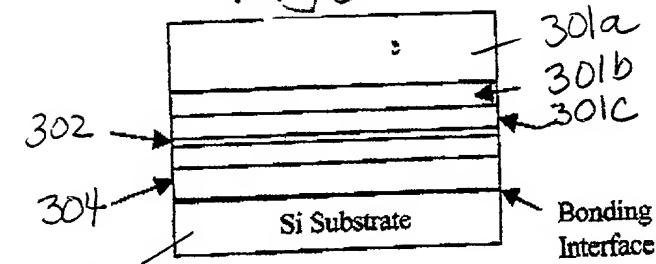
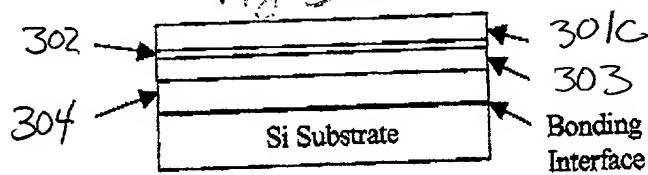


Fig 3 (b)



350

Fig 3 (c)



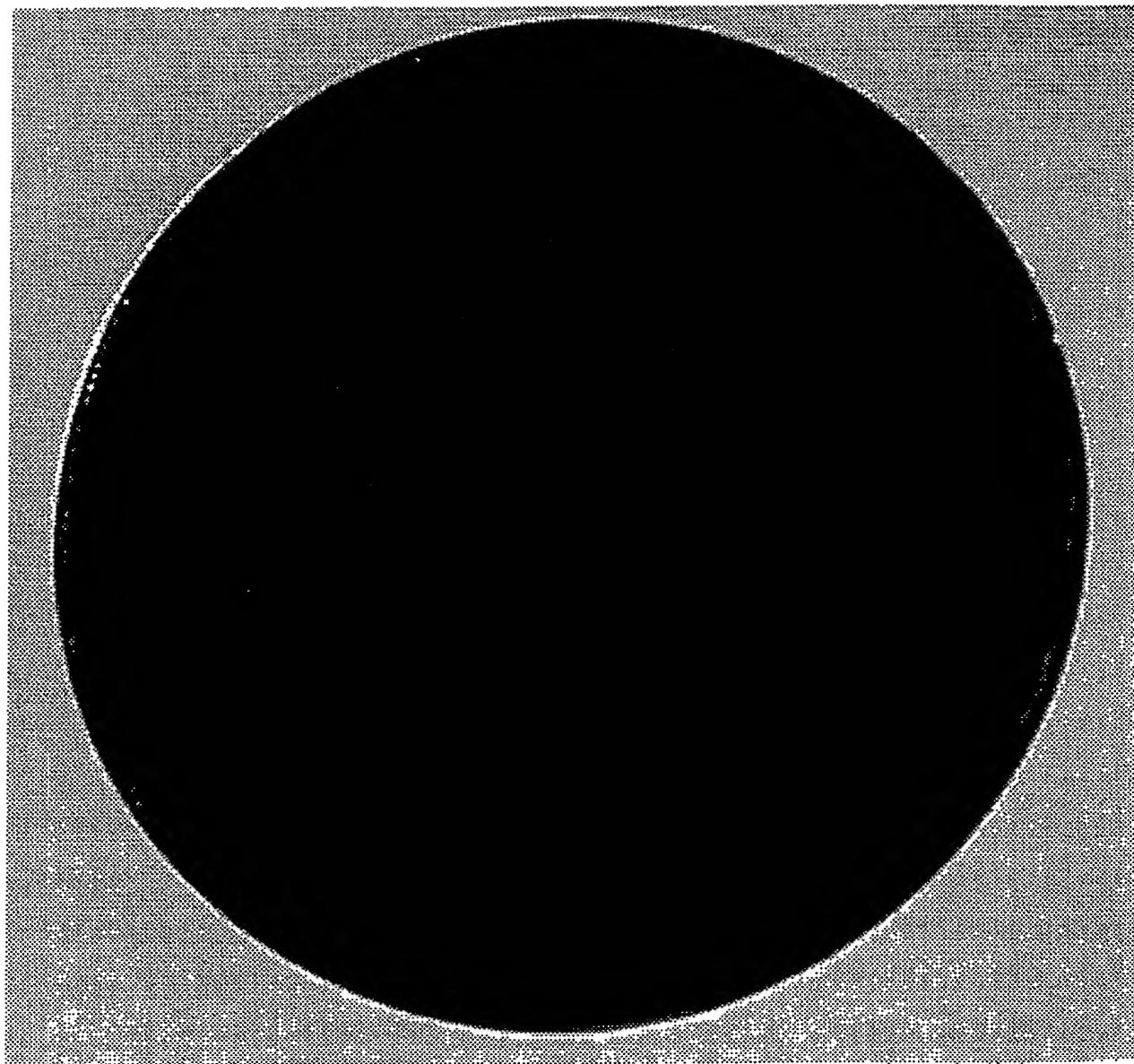


Fig. 4

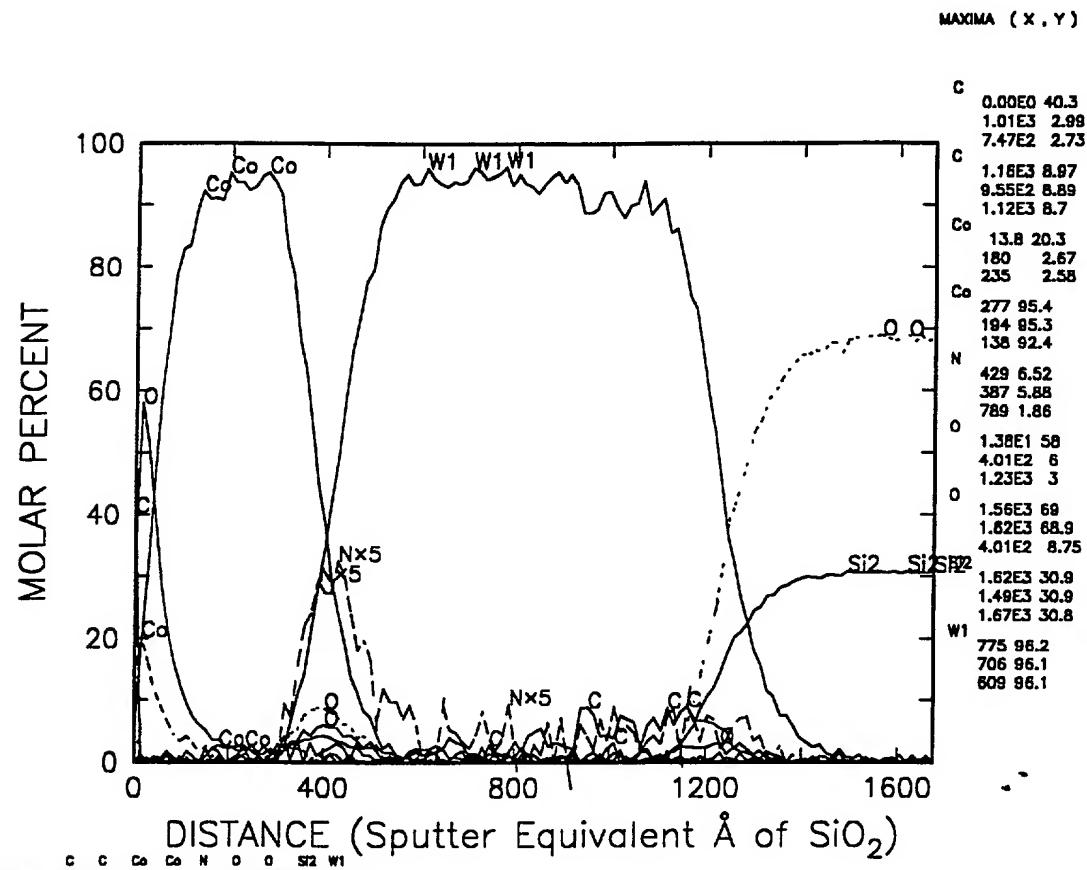


Fig. 5